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(54) **SEMICONDUCTOR CHIP INCLUDING A PLURALITY OF PADS**

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(57) **ABSTRACT**

A semiconductor chip including a plurality of input/output units includes: a plurality of additional pads disposed on a surface of the semiconductor chip, wherein the plurality of additional pads include at least one of a first additional pad to which a ground voltage is applied and a second additional pad to which a power supply voltage is applied; and a plurality of pads disposed on the surface of the semiconductor chip, wherein the plurality of pads include at least one of a first pad to which the ground voltage is applied and a second pad to which the power supply voltage is applied, and further include a third pad through which a signal is input and/or output. The at least one of the first additional pad and the second additional pad is disposed on an input/output unit where the third pad is disposed, among the plurality of input/output units.